

The VDE/VDI-Society Microelectronics, Micro- and Precision Engineering (GMM) in cooperation with BACUS, PMJ, SEMI-Europe, SPIE, and UBC Microelectronics invite you to the

## 25<sup>th</sup> European Mask and Lithography Conference, EMLC 2009

Dresden, Germany  
January 12<sup>th</sup> - January 15<sup>th</sup>, 2009  
[www.emlc2009.com](http://www.emlc2009.com)

The focus of this three-day conference lies on the state-of-the-art of mask technology and lithography, such as mask manufacturing, mask business, lithography & mask applications, emerging mask & lithography technologies, and mask & lithography equipment.

In the past 24 years, this conference has annually brought together scientists, researchers, engineers and developers from around the world to present papers at the forefront of the photomask and lithography. It provides a place where mask makers, mask users and their tool suppliers have the opportunity of becoming acquainted with new developments and results.

### Technical Exhibition

On Tuesday and Wednesday of the conference week we have planned a technical exhibition. Presentation tables and pin boards will be available.

To register for the Technical Exhibition, please use the attached registration form and send it to the conference chair.

### Conference Chairperson and Exhibition Organization

Dr. Uwe Behringer  
UBC Microelectronics  
Auf den Beeten 5  
72119 Ammerbuch, Germany

Phone: +49-171-455 3196  
Fax: +49-7073-50216  
E-Mail: [uwe.behringer.ubc@t-online.de](mailto:uwe.behringer.ubc@t-online.de)

### Abstract Information

Abstract quality will be the basis for selection of conference presentations. The abstracts will be assessed for:

- Originality of work
- Specific results that have been obtained
- Potential impact and interest to the attendees.

Therefore, we highly recommend your abstracts to be composed in a way that they can clearly describe the content of the presentation. The abstracts should consist of at least one page of text (minimum of 1000 words) and meaningful figures. Commercial papers, papers with no new research/development content and papers which lack of significant information will not be accepted. All accepted abstracts will be printed, bound and handed out to the participants of the conference. When writing your abstract, please use the template which can be found at the EMLC-website ([www.emlc2009.com](http://www.emlc2009.com)).

Please send your abstract as a MS-Word® file to the Conference Chair, Dr. Uwe Behringer: [uwe.behringer.ubc@t-online.de](mailto:uwe.behringer.ubc@t-online.de), to the Program Chair, Dr. Wilhelm Maurer: [wilhelm.maurer@infineon.com](mailto:wilhelm.maurer@infineon.com), and to the VDE/VDI-GMM: [gmm@vde.com](mailto:gmm@vde.com).

Please be aware: If you submit an abstract, you agree to submit a manuscript in time.

**Deadline for Abstracts: September 26<sup>th</sup>, 2008**

Authors will be notified of the acceptance of their submissions by **October 24<sup>th</sup> 2008**; further manuscript format, layout instructions and additional information on your presentation will be provided at that time.

### Manuscripts for the Proceedings

Please send in the original of your manuscript latest by

**January 5<sup>th</sup>, 2009**

All manuscripts will be subject to a critical peer review before they are accepted as SPIE/VDE publication and in the SPIE Digital Library. Please note: Late submissions may not be printed in the SPIE/VDE publication or be included in the SPIE Digital Library.

Information on the format of the manuscripts and further details can be found under

[www.emlc2009.com](http://www.emlc2009.com)

### NEW: BEST STUDENT PAPER AWARD

**For the first time, the EMLC 2009 will reward the best Student Paper, based on a generous sponsorship by Carl Zeiss. If applicable, please identify your paper as student paper.**

### Conference Topics

Presentations are being solicited in the following topics:

#### Mask Manufacturing:

- Pattern Generation and Data Preparation
- Photomask- Processes and Materials
- Mask Process Yield
- Photomasks with RET and OPC; PSM
- Mask for NGL: E-Beam, EUV; NIL etc.
- Metrology Tools and Technologies
- Defect Inspection- and Repair Tools
- Cleaning and Pelliclization

#### Mask Business:

- Mask Business and Management
- Direct Write / Maskless Technologies

#### Other Mask Topics:

- Mask Cost and Mask Development Strategy
- Future Mask Demand

#### Lithography and Mask Applications:

- RET, OPC, Double Exposure, MEEF
- Resist
- Mask Defect Printability
- Optical Materials
- Immersion Lithography
- Immersion Defectivity
- Alternate Immersion Fluids

#### Emerging Mask and Lithography Technologies:

- EUV Mask Materials & Processes
- EUV Mask Infrastructure
- NIL
- Double Exposure

#### Mask and Lithography Equipment

## Organizers

VDE/VDI-Society Microelectronics, Micro- and Precision Engineering (GMM)  
Dr.-Ing. Ronald Schnabel  
Stresemannallee 15  
60596 Frankfurt/Main, Germany  
Phone: +49-69-6308-330  
Fax: +49-69-6308-9828  
E-Mail: gmm@vde.com

In cooperation with:  
UBC Microelectronics  
Dr. Uwe Behringer

## Venue: Hilton Hotel in Dresden



Dresden at the river Elbe



Wheel-Boat on the Elbe river. What about a banquet dinner there?

Cover picture: Courtesy of Toppan Photomasks

## The EMLC2009 Steering(\*)and Program Committee of the 25<sup>th</sup> European Mask and Lithography Conference, EMLC 2009

Conference Chair: Dr. U. Behringer, (\*)  
UBC Microelectronics,  
Ammerbuch, Germany

Co-Conference Chairs: Mr. B. Grenon, Brian Consulting,  
Colchester, VT, USA  
Naoya Hayashi (\*), DNP,  
Saitama, Japan

Program Chairs: Dr. W. Maurer, (\*)  
Infineon Technologies, Munich,  
Germany  
Mr. J. Waelpoel, (\*)  
ASML, Veldhoven, Netherlands

Co-Program Chair: Mr. W. Montgomery,  
CNSE assignee at SEMATECH,  
Albany, NY, USA

Dr. M. Arnz, Carl Zeiss SMT AG, Oberkochen, Germany  
Mr. P. Chen, Taiwan Mask Corp., Hsinchu, Taiwan  
Mr. B. Eynon, Samsung assignee at SEMATECH, Albany, NY, USA  
Mr. C. Gale, Applied Materials GmbH, Dresden, Germany  
Dr. A. C. Hourd, Compugraphics International Ltd.,  
Glenrothes, Scotland  
Mr. R. Jonckheere, IMEC, Leuven, Belgium  
Dr. C. K. Kalus, Synopsys GmbH, Aschheim, Germany  
Mr. Lehon, KLA-Tencor Corp., San Jose, CA, USA  
Dr. H. Loeschner, IMS Nanofabrication, Vienna, Austria  
Mr. B. Naber, Cadence Design Systems Inc., San Jose, CA, USA  
Mr. P. Nikolsky, ASML, Veldhoven, The Netherlands  
Dr. C. Pierrat, Cadence Design Systems Inc., San Jose, CA, USA  
Dr. C. Reita, CEA-LETI, Grenoble, France  
Dr. C. Romeo, ST-Microelectronics, Agrate Brianza, Italy  
Prof. Dr. H.-C. Scheer, University of Wuppertal, Germany  
Dr. R. Schnabel (\*), VDE/VDI-GMM, Frankfurt, Germany  
Mrs. I. A. Stolberg, Vistec Electron Beam GmbH, Jena, Germany  
Dr. S. Tedesco, CEA-LETI, Grenoble, France  
Dr. M. Tissier, Toppan Photomasks S.A., Rousset, France  
Mr. G. Unger, Qimonda Dresden GmbH, Germany  
Mr. J. Whittey, Vistec Semiconductor Systems, Oakdale, CA, USA  
Mr. H. Wolf, Photronics MZD GmbH, Dresden, Germany  
Mr. L. Zurbrick, Agilent Technologies Inc., San Jose, CA, USA

# GMM

VDE/VDI-GESELLSCHAFT  
MIKROELEKTRONIK,  
MIKRO- UND FEINWERKTECHNIK



Call for Papers

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